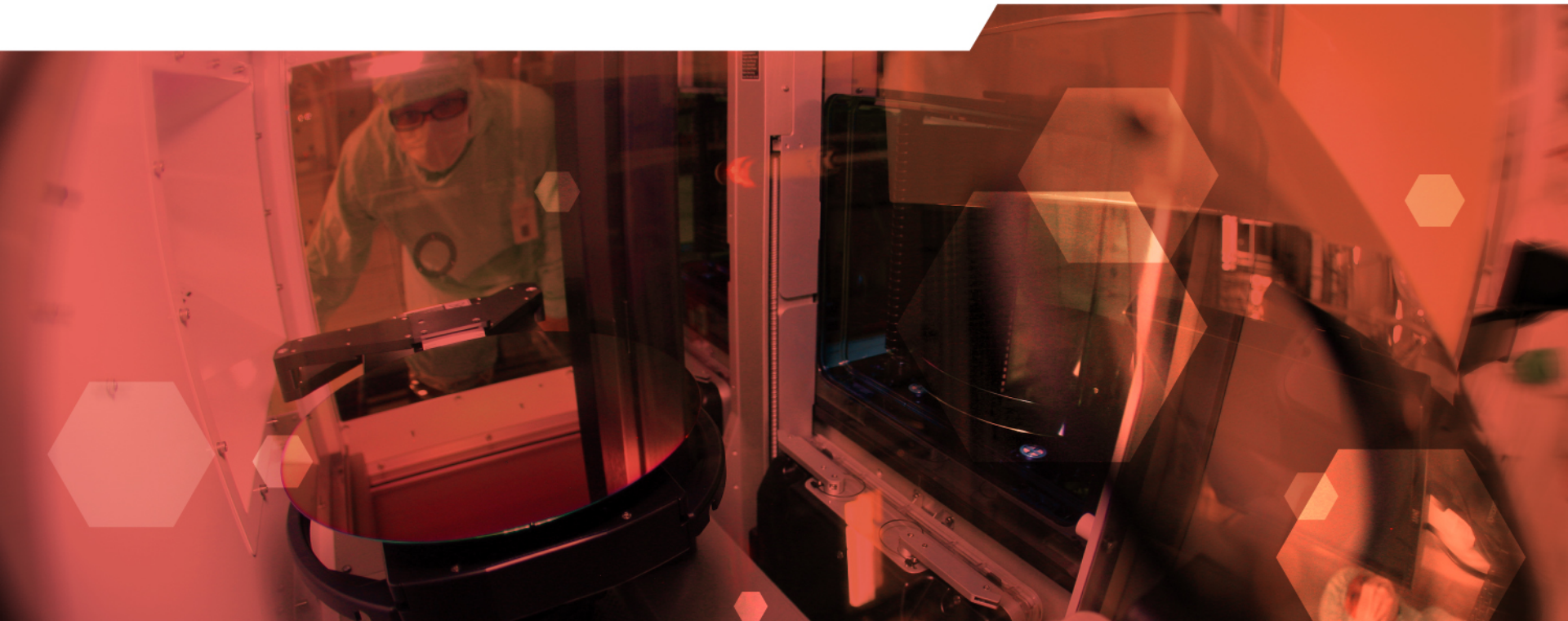


Taiwan TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee

Liaison Report

October 2019

v1



Meeting Information

- Last meeting
 - October 8, 2019 at the SEMI Standards Taiwan Summer 2019 Meetings
 - SEMI Taiwan Office, Zhubei City, Hsinchu County, Taiwan
- Next meeting
 - February 11, 2020 at the SEMI Standards Taiwan Wineter 2019 Meetings
 - SEMI Taiwan Office, Zhubei City, Hsinchu County, Taiwan

<http://www.semi.org/en/standards-events>

Leadership

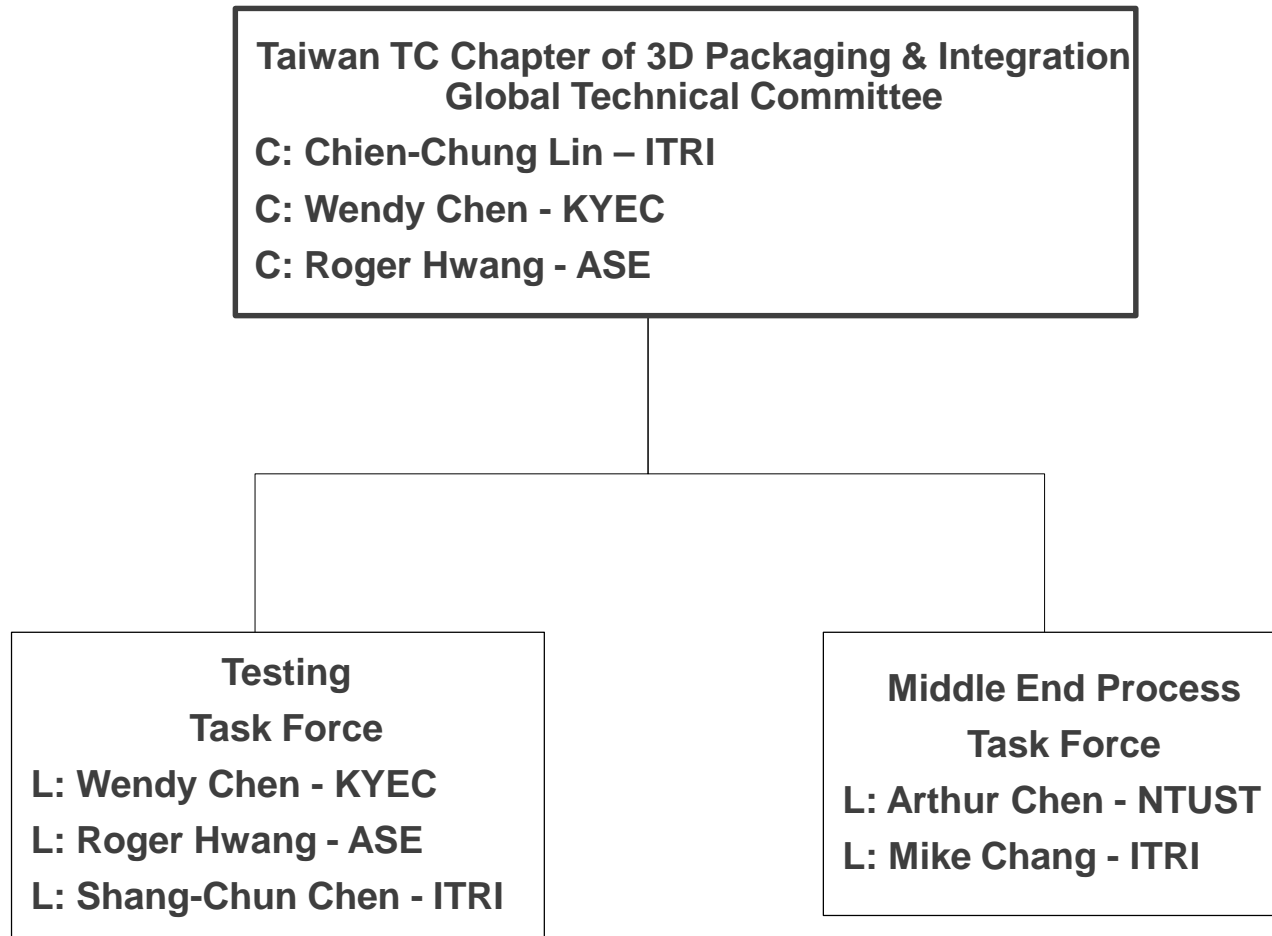
Co-chairs

- Chien-Chung Lin - ITRI
- Wendy Chen - King Yuan Electronics Company
- Roger Hwang - ASE

Leadership Changes

<i>TF/SC/CFG/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
Testing Task Force	Ming-Chin Tsai (KYES)	Wendy Chen (KYES)

Organization Chart



Task Force Highlights

- 3DP&I Middle-End Process Task Force
 - Study the feasibility of submitting a new SNARF for CMP standards in the next TC meeting.
- Testing Task Force
 - Study the feasibility of submitting a new SNARF for tracing each component in 3D IC

Staff Contact

Thank you

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